

60V N-Channel Mosfet

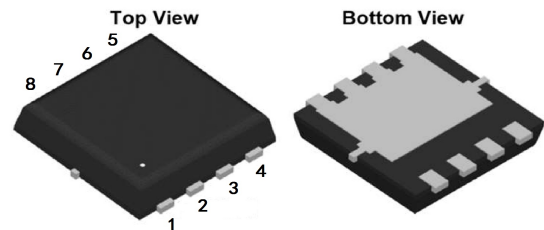
FEATURES

- $R_{DS(ON)} < 6.0m\Omega @ V_{GS} = 10V$
- $R_{DS(ON)} < 11m\Omega @ V_{GS} = 4.5V$

APPLICATIONS

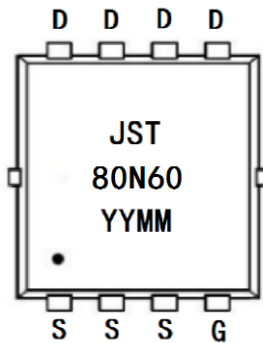
- PWM Applications
- Load Switch
- Power Management

PDFNWB5*6-8L



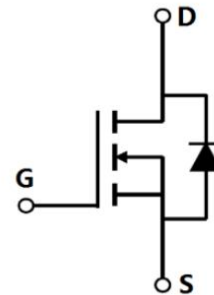
1: S 3: S 5: D 7: D
2: S 4: G 6: D 8: D

MARKING



YYMM:Date Code(year&month)

N-CHANNEL MOSFET



Maximum ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_C = 25^\circ\text{C}$	60	-	V
V_{GS}	Gate-Source Voltage	$T_C = 25^\circ\text{C}$	-	± 20	V
I_D^*	Drain Current	$T_C = 25^\circ\text{C}, V_{GS} = 10\text{V}$	-	60	A
$I_{DM}^{*,**,***}$	Pulsed Drain Current	$T_C = 25^\circ\text{C}, V_{GS} = 10\text{V}$	-	240	A
P_{tot}^*	Total Power Dissipation	$T_C = 25^\circ\text{C}$	-	35	W
T_{stg}	Storage Temperature		- 55	150	$^\circ\text{C}$
T_J	Junction Temperature		-	150	$^\circ\text{C}$
$R_{\theta JA}^*$	Thermal Resistance- Junction to Case		-	3.5	$^\circ\text{C} / \text{W}$

Notes:

- * Surface Mounted on 1 in² pad area, $t \leq 10\text{ sec}$
- ** Pulse width $\leq 10\ \mu\text{s}$, duty cycle $\leq 1\%$
- *** limited by bonding wire

MOSFET ELECTRICAL CHARACTERISTICS Tc=25 °C unless otherwise specified

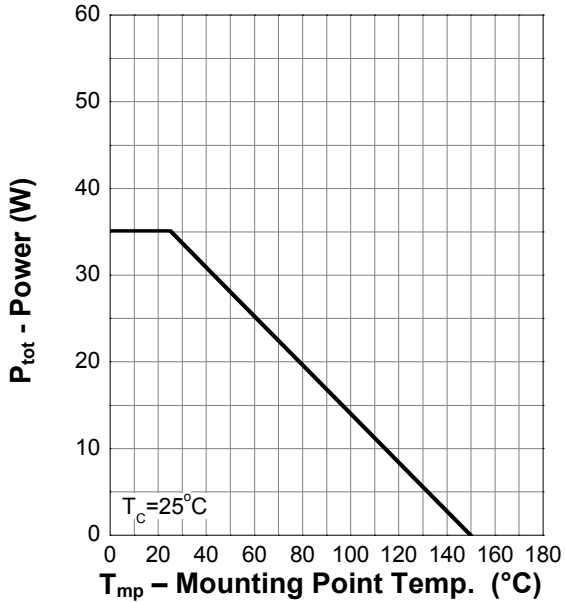
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_{DS} = 250\ \mu\text{A}$	60	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{DS} = 250\ \mu\text{A}$	1.0	-	3.0	V
I_{DSS}	Drain Leakage Current	$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	μA
I_{GSS}	Gate Leakage Current	$V_{GS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA
$R_{DS(ON)}^a$	On-State Resistance	$V_{GS} = 10\text{ V}, I_{DS} = 20\text{ A}$	-	4.8	6	m Ω
		$V_{GS} = 4.5\text{ V}, I_{DS} = 10\text{ A}$	-	8.5	11	
Diode Characteristics						
V_{SD}^a	Diode Forward Voltage	$I_{SD} = 20\text{ A}, V_{GS} = 0\text{ V}$	-	-	1.3	V
t_{rr}	Reverse Recovery Time	$I_{DS} = 20\text{ A}, V_{GS} = 0\text{ V}$ $di_{SD}/dt = 100\text{ A}/\mu\text{s}$	-	62	-	nS
Q_{rr}	Reverse Recovery Charge		-	65	-	μC
Dynamic Characteristics ^b						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 30\text{ V}$ Frequency = 1 MHz	-	2019	-	pF
C_{oss}	Output Capacitance		-	911	-	
C_{riss}	Reverse Transfer Capacitance		-	49	-	
$t_d(on)$	Turn-on Delay Time	$V_{DS} = 30\text{ V}, V_{GEN} = 10\text{ V},$ $R_G = 4.5\ \Omega, R_L = 1.5\ \Omega,$ $I_{DS} = 20\text{ A}$	-	13	-	nS
t_r	Turn-on Rise Time		-	42	-	
$t_d(off)$	Turn-off Delay Time		-	34	-	
t_f	Turn-off Fall Time		-	55	-	
Gate Charge Characteristics ^b						
Q_g	Total Gate Charge	$V_{DS} = 30\text{ V}, V_{GS} = 10\text{ V},$ $I_{DS} = 20\text{ A}$	-	40	-	nC
Q_{gs}	Gate-Source Charge		-	9	-	
Q_{gd}	Gate-Drain Charge		-	10	-	

Notes :

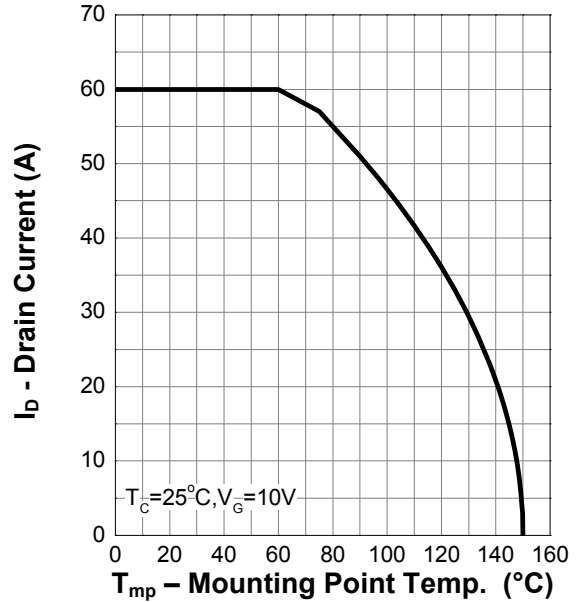
- a : Pulse test ; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$
- b : Guaranteed by design, not subject to production testing

Typical Characteristics

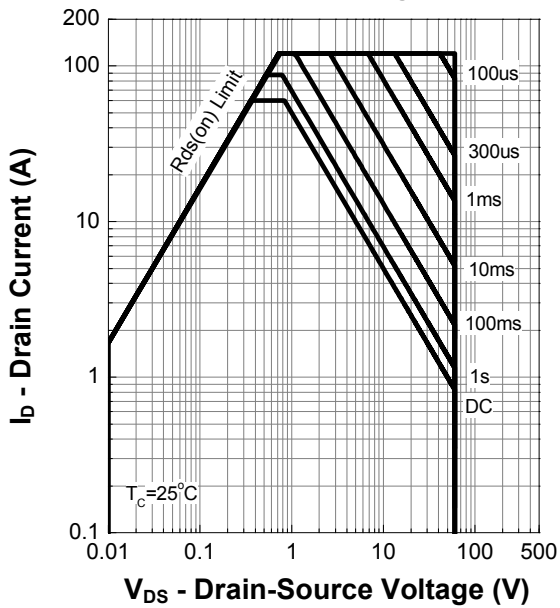
Power Capability



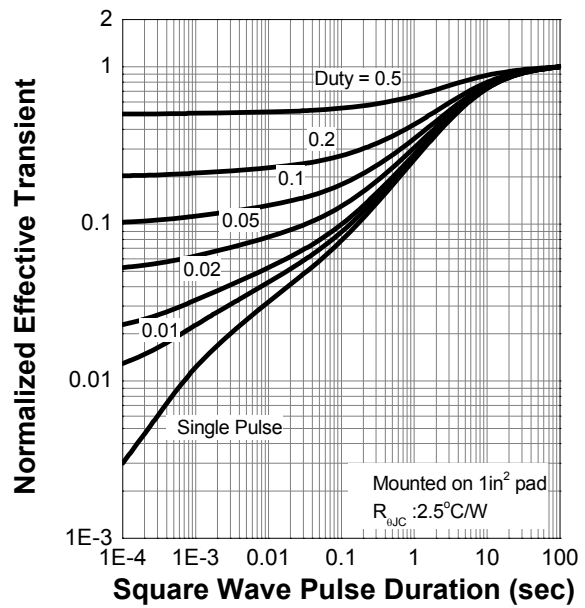
Current Capability

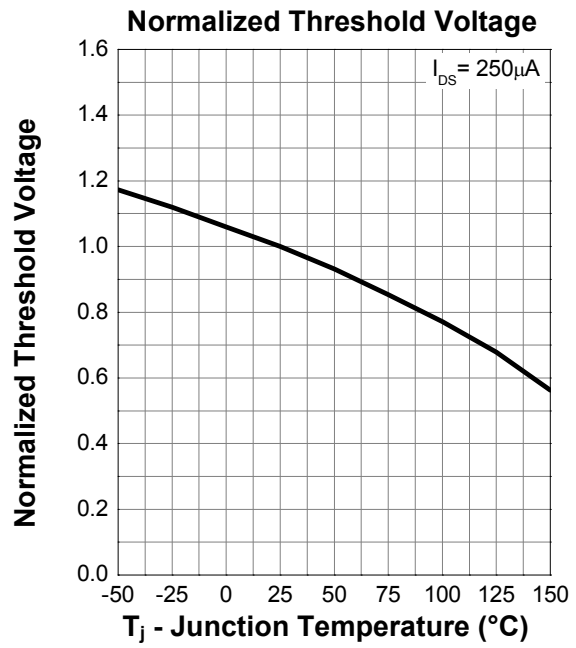
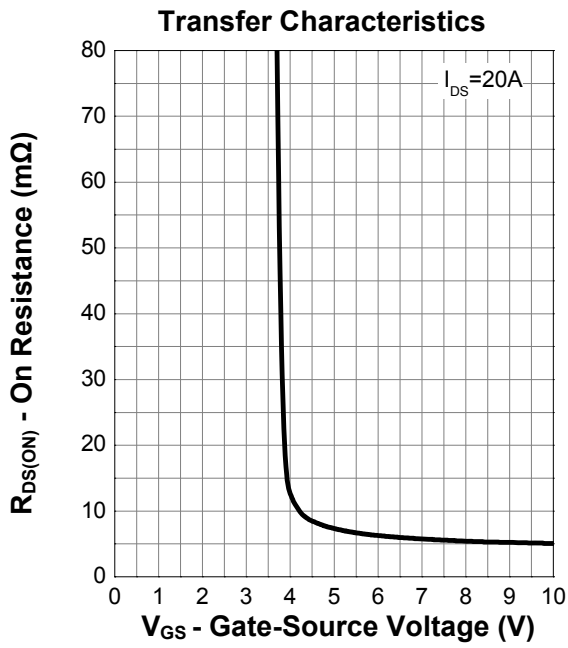
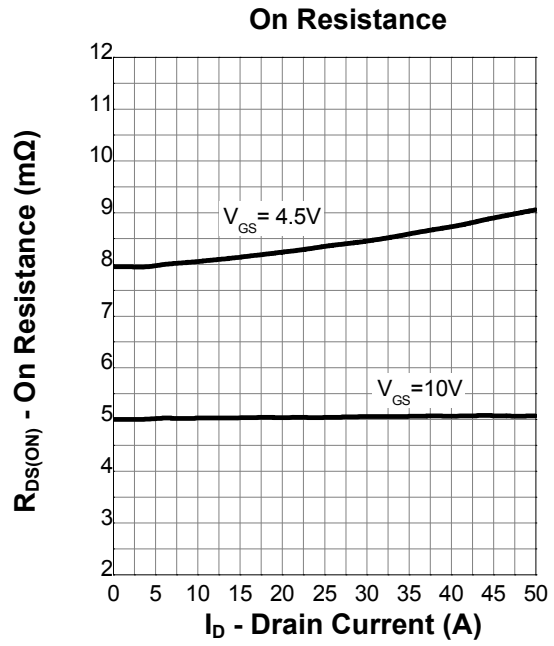
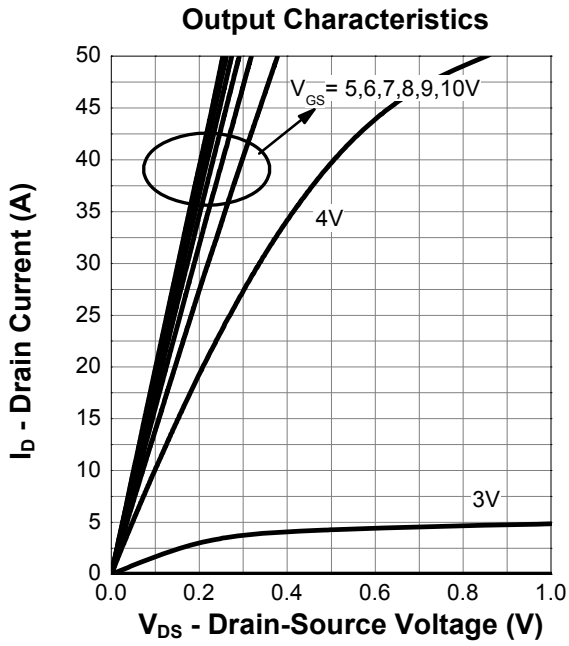


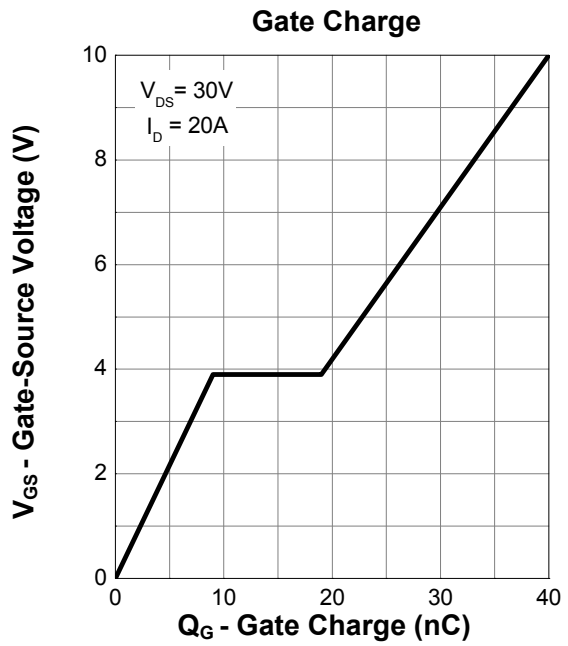
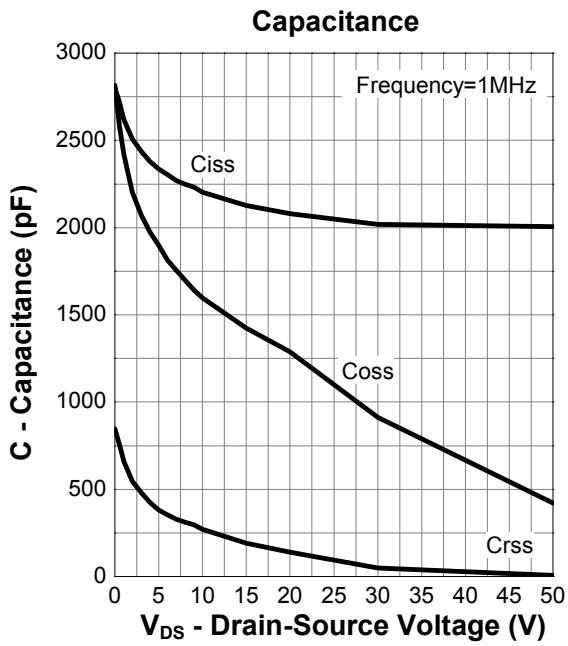
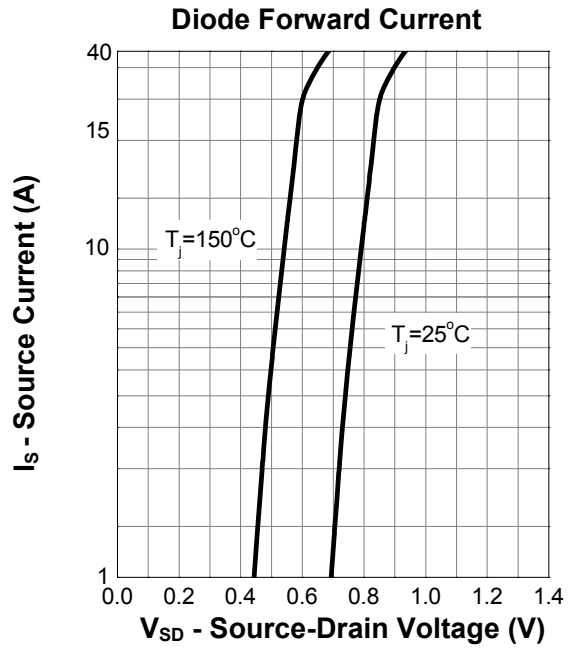
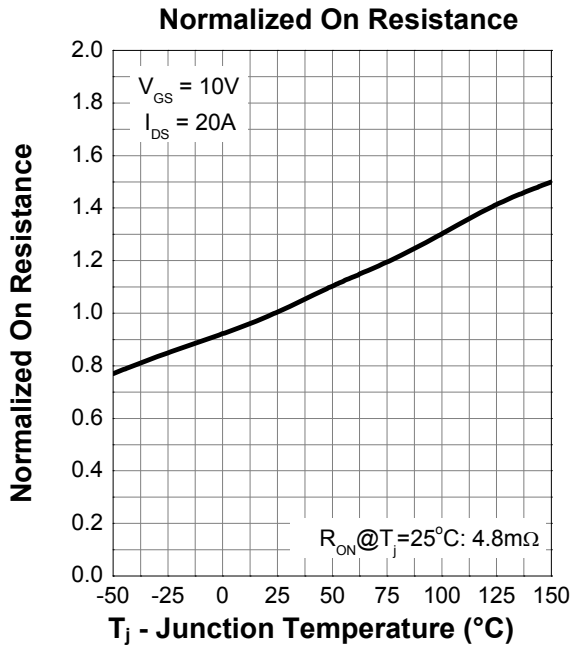
Safe Operating Area



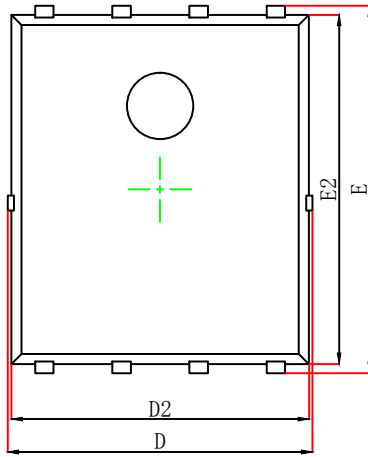
Transient Thermal Impedance



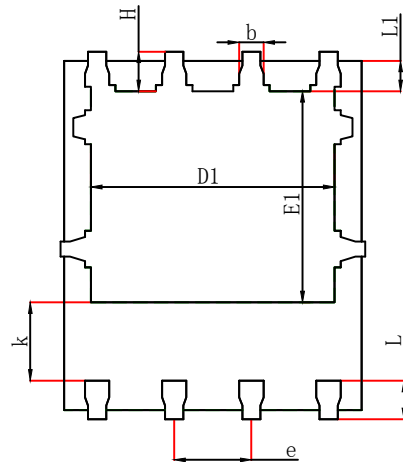




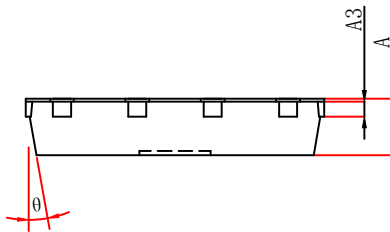
Package Dimension



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°